

**The Law Offices of Mikio Ishimaru**

Intellectual Property Law  
Patents - Licensing - Strategy - & Related Matters  
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To:	Commissioner of Patents	From:	Mikio Ishimaru
Fax:	(703) 872-9306	Pages:	10
Phone:		Date:	February 10, 2004
Re:	U.S. Patent Application Serial No. 10/693,217	CC:	Attorney Docket No.: ST99-002

☒ Revocation of Power of Attorney with New Power of Attorney and Change of Correspondence Address

**IMPORTANT**

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**Certificate of Transmission under 37 CFR 1.8**

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office

on February 10, 2004

  
Tamara Tucker

The following documents are being submitted:

Request and Transmittal

Revocation of Power of Attorney with New Power of Attorney and Change of Correspondence Address

Statement under 37 CFR 3.73(b)

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FEB 12 2004

**OFFICIAL**

Attorney Docket No: ST99-002

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Serial Number 10/693,217  
Filing Date 10/24/2003  
Name of Patentee John Briar  
Title of Invention FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE  
STRUCTURE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**TRANSMITTAL AND REQUEST FOR REVOCATION OF POWER OF ATTORNEY  
WITH NEW POWER OF ATTORNEY AND CHANGE OF CORRESPONDENCE  
ADDRESS**

Dear Sir or Madam:

The applicant respectfully requests that all previous Powers of Attorney be revoked and the office appoint Mikio Ishimaru and all practitioners associated with Customer No. 22898.

Please also change the correspondence address for the above-identified application, U.S. Serial No. 10/693,217 to the address associated with Customer No. 22898.

Assignee of Record is the owner of the entire interest and submits the enclosed Statement under 37CFR 3.73(b).

Enclosed are the following:

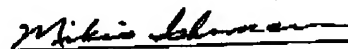
- ☒ Revocation of Power of Attorney with New Power of Attorney and Change of Correspondence Address
- ☒ Statement Under 37 CFR 3.73(b)
- ☒ Certificate of Transmission

Docket Number: ST99-002

Patent

Please charge any shortage in fees due in connection with the filing of this paper to Deposit Account No. 50-0374 and credit any excess fees to such deposit account.

Respectfully submitted,



Mikio Ishimaru  
Reg. No. 27,449  
February 10, 2004

The Law Offices of Mikio Ishimaru  
1110 Sunnyvale-Saratoga Road, Suite A1  
Sunnyvale, CA 94087

**REVOCATION OF POWER OF ATTORNEY WITH NEW POWER OF ATTORNEY AND  
CHANGE OF CORRESPONDENCE ADDRESS**

On behalf of ST Assembly Test Services Pte Ltd, I hereby revoke all previous powers of attorney given in the following U.S. Patents applications:

1. ☐  
In re application of: Sum Kai Wah, Tan Wee Boon, and Jap Liop Jin  
Serial No.: 10/054,423 Filing Date: 1/22/2002  
Title: MULTI-PACKAGE CONVERSION KIT FOR A PICK AND PLACE HANDLER
- The single, original paper is filed for the above patent applications and the public is authorized to inspect and copy the original paper pursuant to 37 CFR 1.12(b).
2. ☐  
In re application of: IL Kwon Shim, Hermes T. Apale, Weddie Racio Aquien, Dario S. Filoteo Jr., Virgil Cotoco Ararao, and Leo Merilo  
Serial No.: 10/055,094 Filing Date: 1/23/2002  
Title: HEAT SPREADER ANCHORING & GROUNDING METHOD & THERMALLY ENHANCED PBGA PACKAGE USING THE SAME
3. ☐  
In re application of: Weddie Racio Aquien, Loreto Y. Cantillep, and Setho Sing Fee  
Serial No.: 10/099,284 Filing Date: 3/15/2002  
Title: HEAT SPREADER HOLE PIN 1 INDENTIFIER
4. ☐  
In re application of: Rajiv Mehta, Liop-Jin Yap, Raymundo M. Camenforte, and Chee-Keong Tan  
Serial No.: 10/140,573 Filing Date: 5/8/2002  
Title: TESTING OF BGA AND OTHER CSP PACKAGES USING PROBING TECHNIQUES
5. ☐  
In re application of: Virgil Cotoco Ararao, Hermes T. Apale, and IL Kwon Shim  
Serial No.: 10/315,533 Filing Date: 12/10/2002  
Title: MOLD CAP ANCHORING METHOD FOR MOLDED FLEX BGA PACKAGES
6. ☐  
In re application of: IL Kwon Shim, Seng Guan Chow, and Gerry Balanon  
Serial No.: 10/462,288 Filing Date: 6/16/2003  
Title: PBGA SUBSTRATE FOR ANCHORING HEAT SINK
7. ☐  
In re application of: John Briar  
Serial No.: 10/043,605 Filing Date: 1/14/2002  
Title: DISPOSABLE MOLD RUNNER GATE FOR SUBSTRATE BASED ELECTRONIC PACKAGES

REVOCATION OF POWER OF ATTORNEY WITH NEW POWER OF ATTORNEY AND CHANGE OF  
CORRESPONDENCE ADDRESS

8. ☐  
In re application of: Tonglong Zhang and John Briar  
Serial No.: 09/726,260 Filing Date: 11/30/2000  
Title: EXTENDED LEAD PACKAGE
9. ☐  
In re application of: IL Kwon Shim, Kambhampati Ramakrishna, and Seng Guan Chow  
Serial No.: 10/256,407 Filing Date: 9/27/2002  
Title: LEADFRAME FOR DIE STACKING APPLICATIONS AND  
RELATED DIE STACKING CONCEPTS
10. ☐  
In re application of: Raymundo M. Camenforte, Dioscoro A. Merilo, and Seng Guan Chow  
Serial No.: 10/339,158 Filing Date: 1/9/2003  
Title: SUPER THIN/SUPER THERMAL BALL GRID ARRAY PACKAGE
11. ☐  
In re application of: John Briar  
Serial No.: 09/640,534 Filing Date: 8/17/2000  
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE  
STRUCTURE
12. ☒  
In re application of: John Briar  
Serial No.: 10/693,217 Filing Date: 10/24/2003  
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE  
STRUCTURE
13. ☐  
In re application of: Raymundo M. Camenforte and John Briar  
Serial No.: 10/371,515 Filing Date: 2/20/2003  
Title: SINGLE UNIT AUTOMATED ASSEMBLY OF FLEX ENHANCED  
GRID ARRAY PACKAGES
14. ☐  
In re application of: Weddie Racio Aquien, John Briar, and Setho Sing Fee  
Serial No.: 10/323,447 Filing Date: 12/19/2002  
Title: ENHANCED BGA GROUNDED HEATSINK
15. ☐  
In re application of: Loreto Y. Cantillep  
Serial No.: 10/236,579 Filing Date: 9/6/2002  
Title: PBGA SINGULATED SUBSTRATE FOR MODEL MELAMINE  
CLEANING
16. ☐  
In re application of: Jeffrey D. Punzalan, Tan Hien Boon, Zheng Zheng, Jae Hak Yee, and  
Byung Joon Han  
Serial No.: 10/462,264 Filing Date: 6/16/2003  
Title: GROUND PLANE FOR EXPOSED PACKAGE

REVOCATION OF POWER OF ATTORNEY WITH NEW POWER OF ATTORNEY AND CHANGE OF  
CORRESPONDENCE ADDRESS

17. ☐  
In re application of: IL Kwon Shim, Hermes T. Apale, and Gerry Balanon  
Serial No.: 10/119,920 Filing Date: 4/10/2002  
Title: HEAT SPREADER INTERCONNECT METHODOLOGY FOR  
THERMALLY ENHANCED PBGA PACKAGES

18. ☐  
In re application of: Jian Jun Li  
Serial No.: 10/224,151 Filing Date: 8/20/2002  
Title: TEST COUPON PATTERN DESIGN TO CONTROL  
MULTILAYER SAW SINGULATED PLASTIC BALL GRID  
ARRAY SUBSTRATE MIS-REGISTRATION

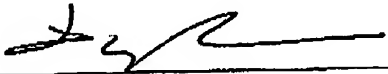
19. ☐  
In re application of: Yong Gang Jin and Won Sun Shin  
Serial No.: 10/151,977 Filing Date: 5/21/2002  
Title: TORCH BUMP

20. ☐  
In re application of: IL Kwon Shim, Jian Jun Li, and Sheila Marie L. Alvarez  
Serial No.: 10/279,900 Filing Date: 10/24/2002  
Title: COST EFFECTIVE SUBSTRATE FABRICATION FOR FILP-CHIP  
PACKAGES

- ☒ I hereby appoint Mikio Ishimaru and all practitioners associated with Customer  
Number 22898
- ☒ Please change the Correspondence Address for the above identified Patents and  
Applications to the address associated with Customer Number 22898
- ☒ Assignee of record is owner of the entire interest (see 37 CFR 3.71(b)), and submits  
the enclosed Statement under 37 CFR 3.73(b).

The undersigned (whose title is supplied below) is empowered to sign below on behalf of the  
Assignee.

February 3, 2004  
Date

  
Signature

Tan Lay Koon

Typed or printed name

President & CEO

Title

STATEMENT UNDER 37 CFR 3.73(b)

ST Assembly Test Services Pte Ltd, a Singapore corporation states that it is the assignee of the entire right, title, and interest of the patent applications identified below by virtue of the chain of title from the inventors to the current assignee as shown below:

1. ☐  
Inventors: Sum Kai Wah, Tan Wee Boon, and Jap Liop Jin  
Serial No.: 10/054,423 Filing Date: 1/22/2002  
Title: MULTI-PACKAGE CONVERSION KIT FOR A PICK AND PLACE HANDLER  
Chain of Title: From: Wah et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 012547/0179  
  
The single, original paper is filed for the above patent application and the public is authorized to inspect and copy the original paper pursuant to 37 CFR 1.12(b).
2. ☐  
Inventors: IL Kwon Shim, Hermes T. Apale, Weddie Racio Aquien, Dario S. Filoteo Jr., Virgil Cotoco Ararao, and Leo Merilo  
Serial No.: 10/055,094 Filing Date: 1/23/2002  
Title: HEAT SPREADER ANCHORING & GROUNDING METHOD & THERMALLY ENHANCED PBGA PACKAGE USING THE SAME  
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 012560/0078
3. ☐  
Inventors: Weddie Racio Aquien, Loreto Y. Cantillep, and Setho Sing Fee  
Serial No.: 10/099,284 Filing Date: 3/15/2002  
Title: HEAT SPREADER HOLE PIN 1 IDENTIFIER  
Chain of Title: From: Aquien et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 011013/0053
4. ☐  
Inventors: Rajiv Mehta, Liop-Jin Yap, Raymundo M. Camenforte, and Chee-Keong Tan  
Serial No.: 10/140,573 Filing Date: 5/8/2002  
Title: TESTING OF BGA AND OTHER CSP PACKAGES USING PROBING TECHNIQUES  
Chain of Title: From: Mehta et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 9782/0373

## STATEMENT UNDER 37 CFR 3.73(b)

5. ☐  
Inventors: Virgil Cotoco Ararao, Hermes T. Apale, and IL Kwon Shim  
Serial No.: 10/315,533 Filing Date: 12/10/2002  
Title: MOLD CAP ANCHORING METHOD FOR MOLDED FLEX BGA PACKAGES  
Chain of Title: From: Ararao et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 013572 / 0799
6. ☐  
Inventors: IL Kwon Shim, Seng Guan Chow, and Gerry Balanon  
Serial No.: 10/462,288 Filing Date: 6/16/2003  
Title: PBGA SUBSTRATE FOR ANCHORING HEAT SINK  
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 012212/0615
7. ☐  
Inventor: John Briar  
Serial No.: 10/043,605 Filing Date: 1/14/2002  
Title: DISPOSABLE MOLD RUNNER GATE FOR SUBSTRATE BASED ELECTRONIC PACKAGES  
Chain of Title: From: Briar To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 9203/0956
8. ☐  
Inventors: Tonglong Zhang and John Briar  
Serial No.: 09/726,260 Filing Date: 11/30/2000  
Title: EXTENDED LEAD PACKAGE  
Chain of Title: From: Zhang et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 9296/0271
9. ☐  
Inventors: IL Kwon Shim, Kambhampati Ramakrishna, and Seng Guan Chow  
Serial No.: 10/256,407 Filing Date: 9/27/2002  
Title: LEADFRAME FOR DIE STACKING APPLICATIONS AND RELATED DIE STACKING CONCEPTS  
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 013348/0051
10. ☐  
Inventors: Raymundo M. Camenforte, Dioscoro A. Merilo, and Seng Guan Chow  
Serial No.: 10/339,158 Filing Date: 1/9/2003  
Title: SUPER THIN/SUPER THERMAL BALL GRID ARRAY PACKAGE  
Chain of Title: From: Camenforte et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 011883/0196



## STATEMENT UNDER 37 CFR 3.73(b)

11. ☐  
Inventor: John Briar  
Serial No.: 09/640,534 Filing Date: 8/17/2000  
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE  
STRUCTURE  
Chain of Title: From: Briar To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 011147/0398
12. ☒  
Inventor: John Briar  
Serial No.: 10/693,217 Filing Date: 10/24/2003  
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE  
STRUCTURE  
Chain of Title: From: Briar To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 011147/0398
13. ☐  
Inventors: Raymundo M. Camenforte and John Briar  
Serial No.: 10/371,515 Filing Date: 2/20/2003  
Title: SINGLE UNIT AUTOMATED ASSEMBLY OF FLEX ENHANCED  
GRID ARRAY PACKAGES  
Chain of Title: From: Camenforte et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 011310/0481
14. ☐  
Inventors: Weddie Racio Aquien, John Briar, and Setho Sing Fee  
Serial No.: 10/323,447 Filing Date: 12/19/2002  
Title: ENHANCED BGA GROUNDED HEATSINK  
Chain of Title: From: Aquien et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 011793/0768
15. ☐  
Inventor: Loreto Y. Cantillep  
Serial No.: 10/236,579 Filing Date: 9/6/2002  
Title: PBGA SINGULATED SUBSTRATE FOR MODEL MELAMINE  
CLEANING  
Chain of Title: From: Cantillep To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 011125/0469
16. ☐  
Inventors: Jeffrey D. Punzalan, Tan Hien Boon, Zheng Zheng, Jae Hak Yee, and  
Byung Joon Han  
Serial No.: 10/462,264 Filing Date: 6/16/2003  
Title: GROUND PLANE FOR EXPOSED PACKAGE  
Chain of Title: From: Punzalan et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 012656/0753

## STATEMENT UNDER 37 CFR 3.73(b)

17. ☐

Inventors: IL Kwon Shim, Hermes T. Apale, and Gerry Balanon  
Serial No.: 10/119,920 Filing Date: 4/10/2002  
Title: HEAT SPREADER INTERCONNECT METHODOLOGY FOR  
THERMALLY ENHANCED PBGA PACKAGES  
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 012791/0604

18. ☐

Inventor: Jian Jun Li  
Serial No.: 10/224,151 Filing Date: 8/20/2002  
Title: TEST COUPON PATTERN DESIGN TO CONTROL MULTILAYER  
SAW SINGULATED PLASTIC BALL GRID ARRAY SUBSTRATE  
MIS-REGISTRATION  
Chain of Title: From: Li To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 013218/0397

19. ☐

Inventors: Yong Gang Jin and Won Sun Shin  
Serial No.: 10/151,977 Filing Date: 5/21/2002  
Title: TORCH BUMP  
Chain of Title: From: Jin et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 012923/0359

20. ☐

Inventors: IL Kwon Shim, Jian Jun Li, and Sheila Marie L. Alvarez  
Serial No.: 10/279,900 Filing Date: 10/24/2002  
Title: COST EFFECTIVE SUBSTRATE FABRICATION FOR FILP-CHIP  
PACKAGES  
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd  
Recorded in the Patent and Trademark Office at reel/frame: 013434/0473

The undersigned (whose title is supplied below) is empowered to sign below on behalf of the assignee.

February 3, 2004  
Date

  
Signature

Tan Lay Koon

Typed or printed name

President & CEO

Title